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		APPLICANT: Narendar et al.	
		GROUP ART UNIT: 1755	EXAMINER: Karl E. Group
Sheet	1	of	1

U.S. PATENT DOCUMENTS

Examiner's Initials	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication or of issue of Cited Document MM-DD-YYYY
		Number	Kind Code		
<i>h</i>		*5,834,387		Divakar et al.	11-10-1998

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Examiner's Initials	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document (not necessary)	Date of Publication of Cited Document MM-DD-YYYY	Translation (Y/N)
		Office/ Country	Number	Kind Code			
<i>h</i>		EP	1 184 355	A1	Toshiba Ceramics Co., Ltd.	03-06-2002	
<i>h</i>		JP	2002 338366	A	Tokai Konetsu Kogyo Co., Ltd.	11-27-2002	Abstract
<i>h</i>		CA	2 466 183	A1	Bridgestone Corporation, JP	05-15-2003	

OTHER ART — NON PATENT LITERATURE DOCUMENTS

Examiner's Initials	Cite No.	Include name of the author (in CAPITAL LETTERS) title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, relevant page(s), volume-issue number(s), publisher, city and/or country where published.	Translation (Y/N)
<i>h</i>		H. RAUH, "Atlas for Characterization of Defects in Silicon," Wacker Siltronic AG, Burghausen, Germany, pp. 1-64, 2004.	
<i>h</i>		R. F. BUCKLEY et al., "Design and Analysis of a Semiconductor Wafer Processing System for 30 mm Wafers," MS Thesis submitted to the Worcester Polytechnic Institute, 12/22/99, pp. i-62.	
<i>h</i>		B. LEROY et al., "Warping of Silicon Wafers," <i>Journal Electrochemical Society</i> , Vol. 127, No. 4, April 1980, pp. 961-970.	
<i>h</i>		M. SCHREMS et al., "Simulation of Temperature Distributions During Fast Thermal Processing," <i>Journal Electrochemical Society</i> , Semiconductor Silicon 1994, pp. 1050-1059.	
<i>h</i>		NILSON et al., "Scaling wafer stresses and thermal processes to large wafers," <i>Thin Solid Films</i> 315, 1998, pp. 286-293.	
<i>h</i>		PETER VAN ZANT, "Microchip Fabrication: A Practical Guide to Semiconductor Processing," McGraw Hill, Fourth Edition, 1990, chapters 3-7.	
<i>h</i>		SHIGLEY et al., "Mechanical Engineering Design," McGraw Hill, copyright 1989, p. 62, p. 159.	
<i>h</i>		Machinery Handbook, 24 th Edition, Industrial Press, Copyright 1992, pp. 1598-1603.	

EXAMINER <i>[Signature]</i>	DATE CONSIDERED <i>1-18-06</i>
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#EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

*a copy of this reference is not provided because a copy of this reference need not be provided as the reference is a published U.S. Patent or U.S. Patent application and the present application was filed after June 30, 2003.